



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eichelberger et al.

Confirmation No.: 4726

#8m

Serial No.: 09/502,078

Group Art Unit: 2814

Filed: 02/10/00

Examiner: Pizarro Crespo, M.

Title: INTEGRATED CIRCUIT STRUCTURES AND METHODS EMPLOYING A
LOW MODULUS HIGH ELONGATION PHOTODIELECTRIC

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Box Issue Fee, Attn.: Official Draftsperson, Washington, D.C. 20231, on May 17, 2002.

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Kevin P. Radigan, Esq.
Attorney for Applicants
Reg. No. 31,789

To: BOX ISSUE FEE
Commissioner for Patents
Washington, D.C. 20231


Attention: Official Draftsperson

Dear Sir:

Substitute formal drawings 1/10 through 10/10 for the above-designated application is submitted herewith in compliance with

the Notice of Allowability mailed February 26, 2002 in connection with the above-designated application.

Respectfully submitted,



Kevin P. Radigan Esq.
Reg. No. 31,789

Dated: May 17, 2002

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